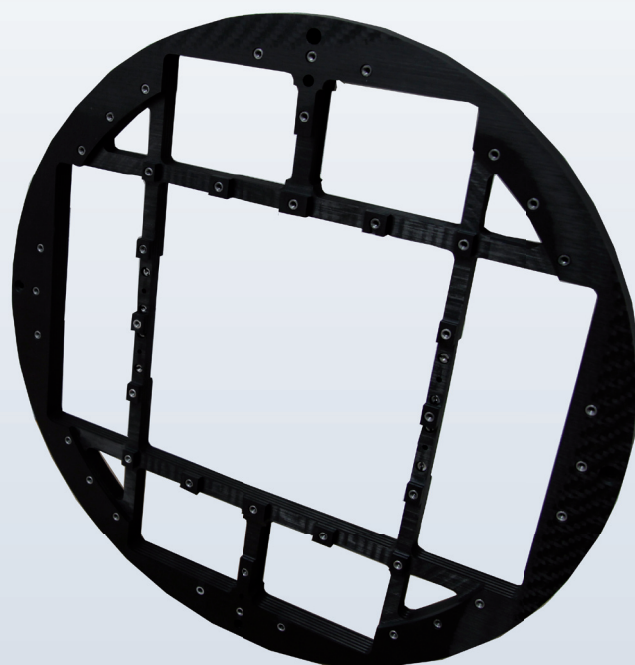
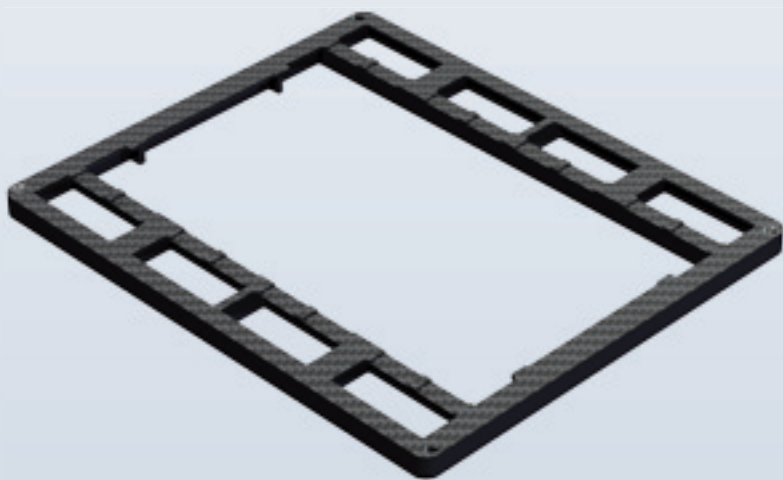


composite technology

key solution
cooperation with customers
for design + manufacture

- a result of more than 10 years' experience
- revolutionary interfacing solution
- up to 80% weight reduction
- lowest thermal expansion

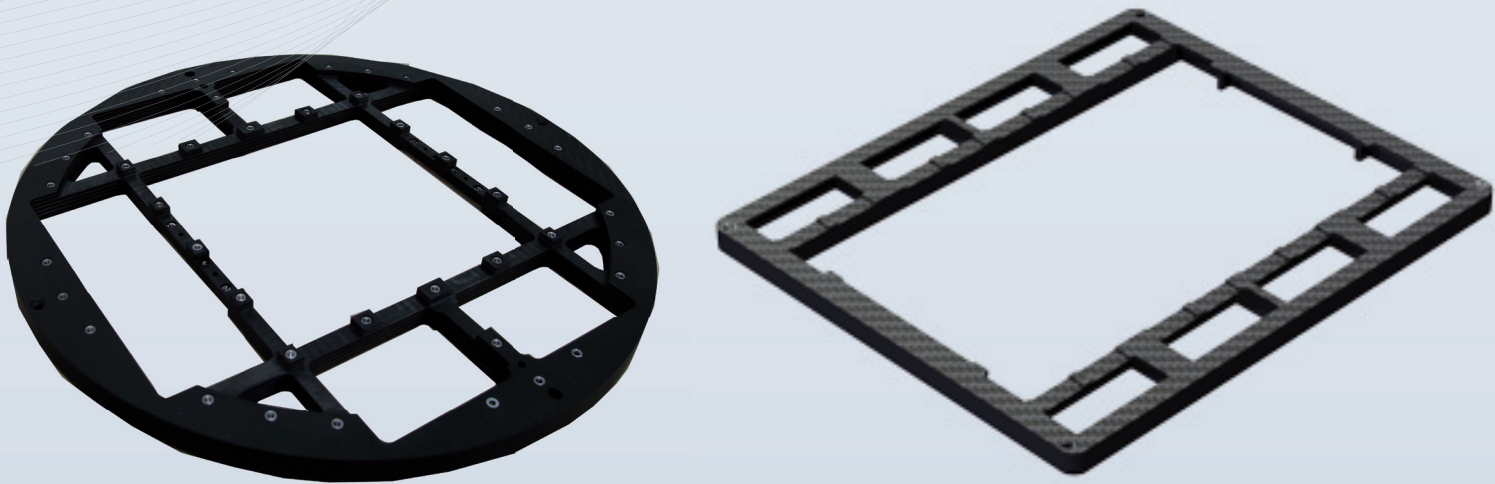


	composite	stainless steel <small>based on 1.4305</small>	aluminium <small>based on AlMg4.5Mn</small>
density <small>g/cm³</small>	up to 1.5*	7.9	2.8
e-module <small>N/mm²</small>	up to 105,000*	190,000	71,000
tensile strength <small>N/mm²</small>	1,300*	520	275
thermal expansion <small>10⁻⁶/K</small>	up to 1-2*	500	23.9

* figures may vary based on specific characteristics in fiber and lamination directions

key features

- highest stability at lowest weight
- various adaptable PCB designs
- controllable thermal expansion
- weight reduction up to 50% compared to aluminium
- enhanced stiffness up to 100% compared to aluminium
- weight reduction up to 80% compared to stainless steel
- highest thermal properties depending on lamination directions
- soak-time reduction



Please contact our sales team for further and/or detailed information.